

Features

- Trench Power LV MOSFET technology
- AEC-Q101 Qualified
- ESD Protected up to 2KV (HBM)
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note1)
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

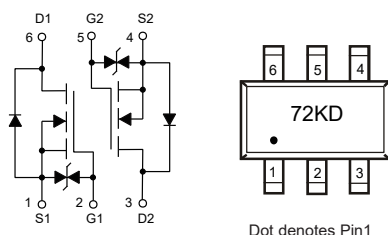
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 515°C/W Junction to Ambient (Steady-State) (Note2)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	$T_A=25^\circ\text{C}$	220	mA
	$T_A=100^\circ\text{C}$	140	
Pulsed Drain Current (Note3)	I_{DM}	0.88	A
Total Power Dissipation (Note4)	P_D	0.24	W

Note:

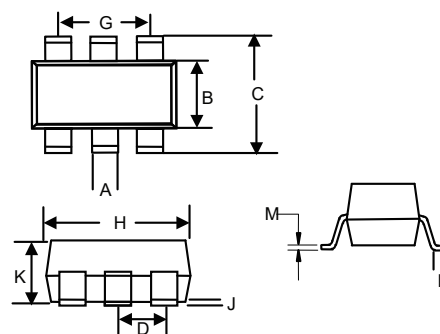
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The Power dissipation P_{DSM} is based on $R_{\theta JA} \leq 10\text{s}$ and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction to Ambient thermal resistance.

Internal Structure and Marking Code



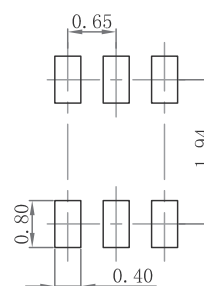
DUAL N-CHANNEL MOSFET

SOT-363



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.006	0.014	0.15	0.35	
B	0.045	0.053	1.15	1.35	
C	0.079	0.096	2.00	2.45	
D	0.026		0.65		TYP.
G	0.047	0.055	1.20	1.40	
H	0.071	0.087	1.80	2.20	
J	-----	0.004	-----	0.10	
K	0.031	0.043	0.80	1.10	
L	0.010	0.018	0.26	0.46	
M	0.003	0.006	0.08	0.15	

SUGGESTED SOLDER PAD LAYOUT



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	60			V
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±10	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =48V, V _{GS} =0V			1	μA
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.8	1.5	2.4	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =300mA		1.1	2.5	Ω
		V _{GS} =4.5V, I _D =200mA		1.3	3	
Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =300mA		0.9	1.2	V
Reverse Recovery Time	t _{rr}	I _F =1A, dI _F /dt=100A/μs		15		ns
Reverse Recovery Charge	Q _{rr}			3.9		nC
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1MHz		25		pF
Output Capacitance	C _{oss}			8		
Reverse Transfer Capacitance	C _{rss}			4		
Total Gate Charge	Q _g	V _{DS} =30V, V _{GS} =10V, I _D =1A		1.75		nC
Gate-Source Charge	Q _{gs}			1		
Gate-Drain Charge	Q _{gd}			0.25		
Turn-On Delay Time	t _{d(on)}	V _{DD} =30V, V _{GS} =10V R _{GEN} =3Ω, I _{DS} =1A		4.6		ns
Turn-On Rise Time	t _r			20		
Turn-Off Delay Time	t _{d(off)}			10.5		
Turn-Off Fall Time	t _f			25.5		

Curve Characteristics

Fig. 1 - Typical Output Characteristics

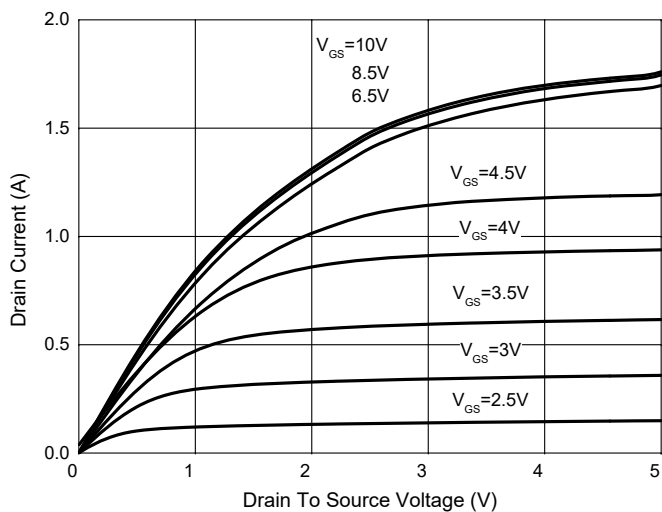


Fig. 2 - Transfer Characteristics

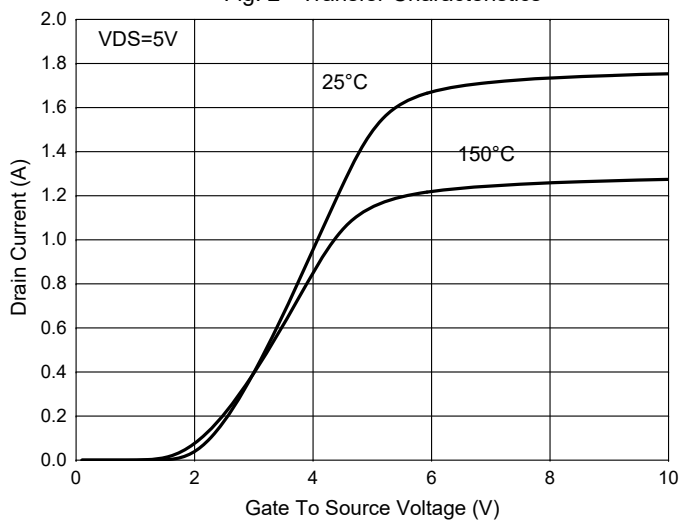


Fig. 3- Capacitance Characteristics

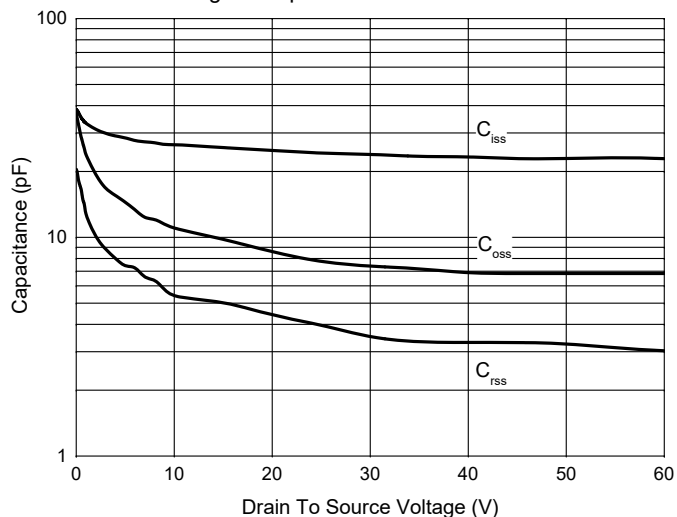


Fig. 4 - GateCharge

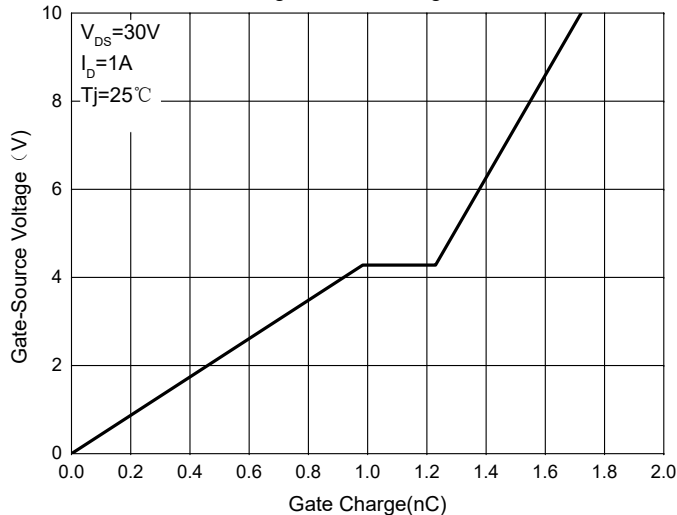


Fig. 5 - $R_{DS(ON)}$ — V_{GS}

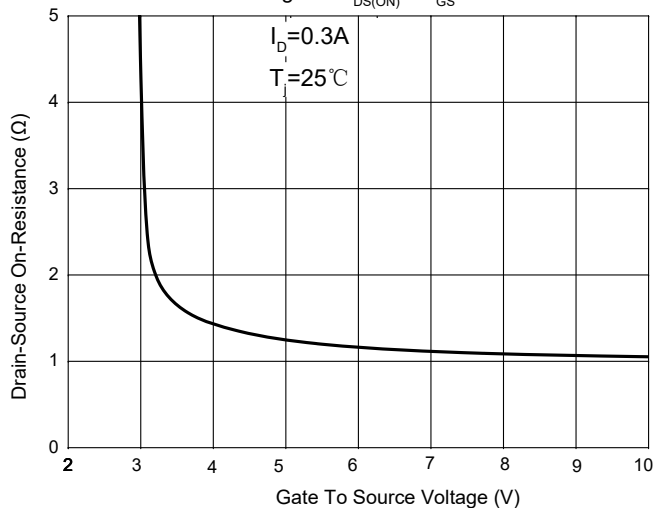
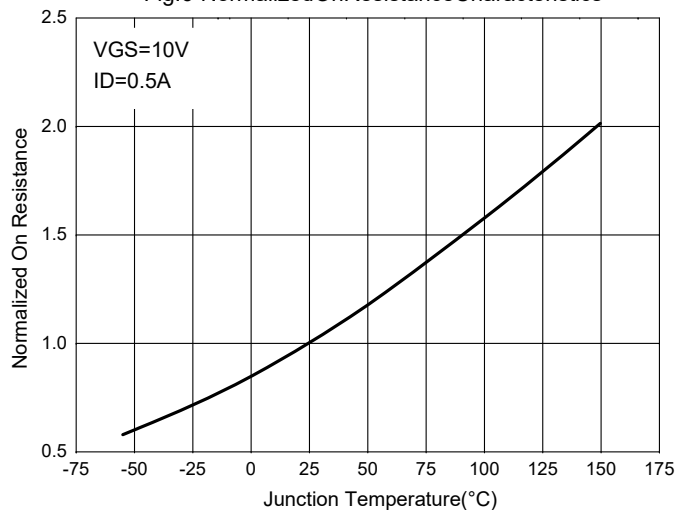
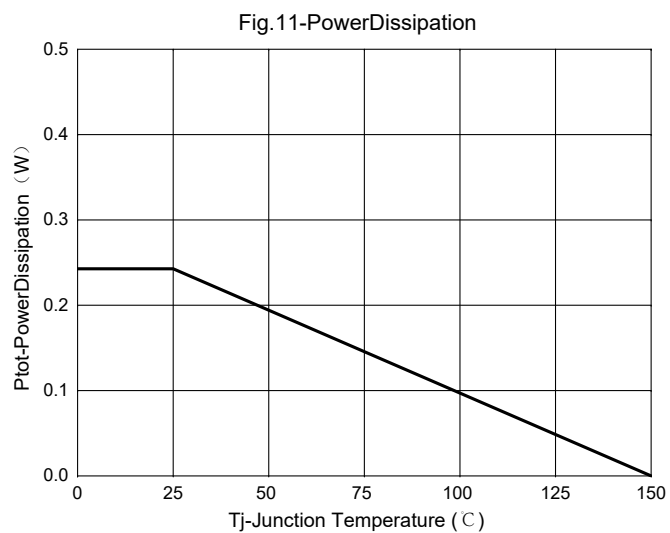
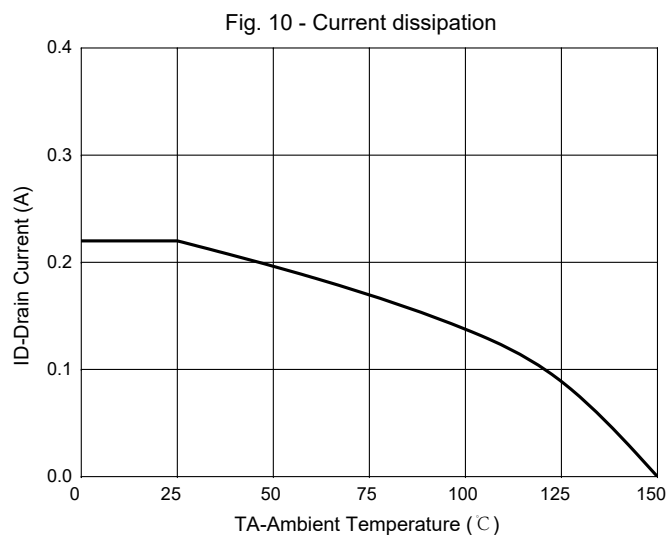
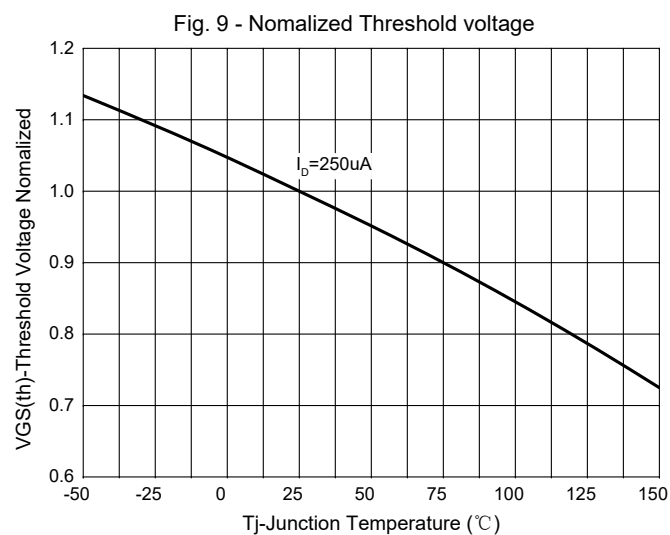
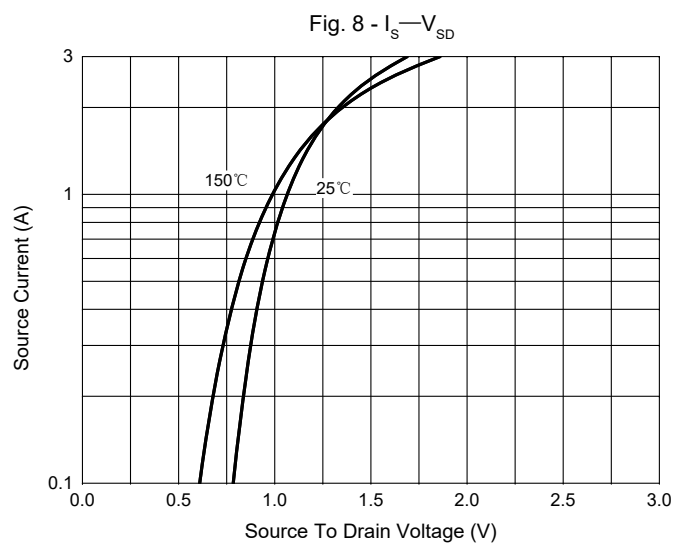
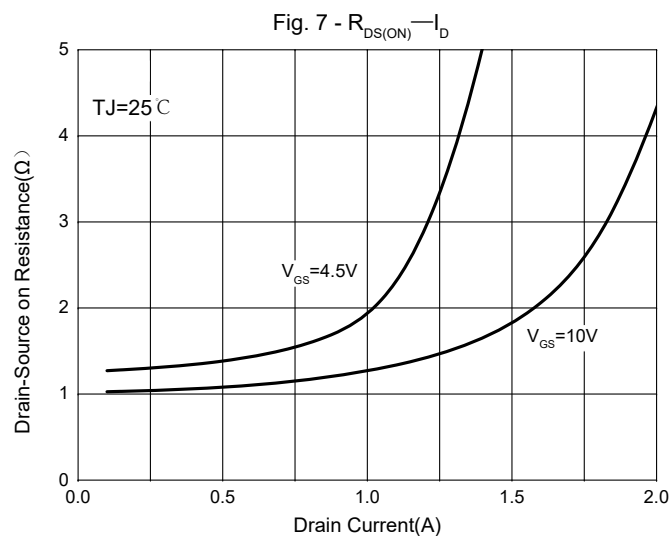


Fig.6-NormalizedOnResistanceCharacteristics



Curve Characteristics



Curve Characteristics

Fig. 12 - Safe Operation Area

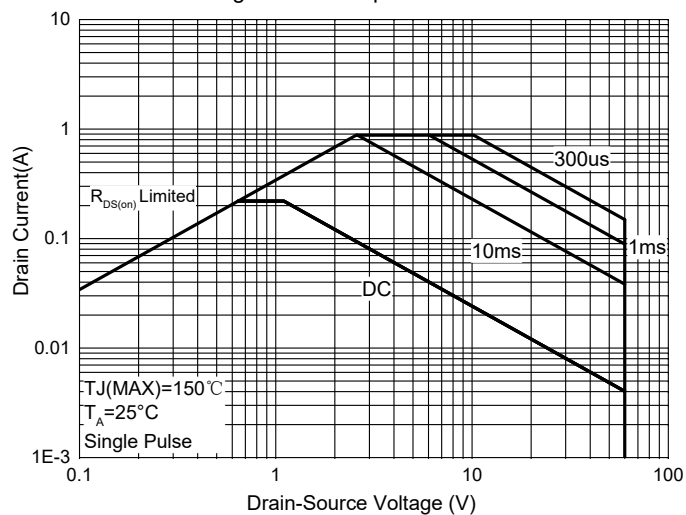
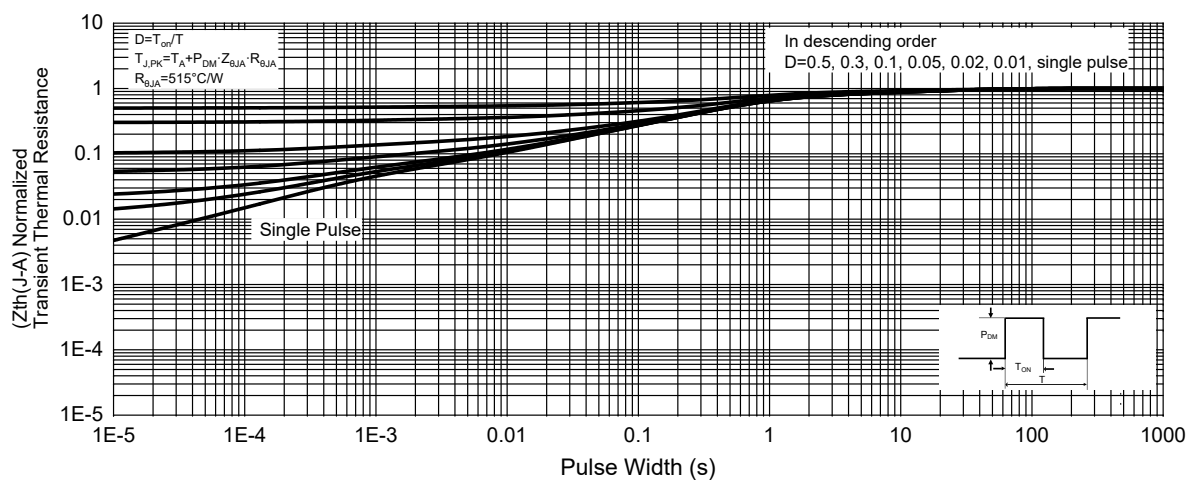


Fig. 13 -Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
2N7002KDWBQ-TP	Tape&Reel: 3Kpcs/Reel

Revision History

Datasheet status	Version No	Release date	Update content
New product datasheet	Rev4-1	20221220	

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